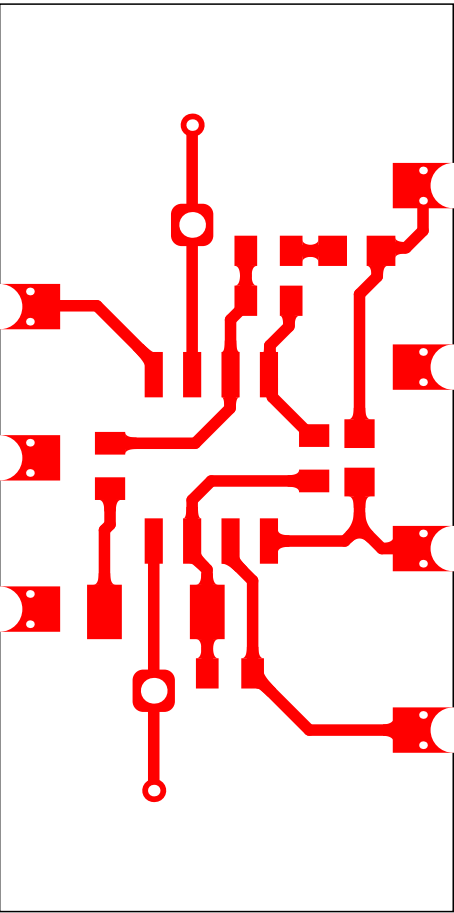
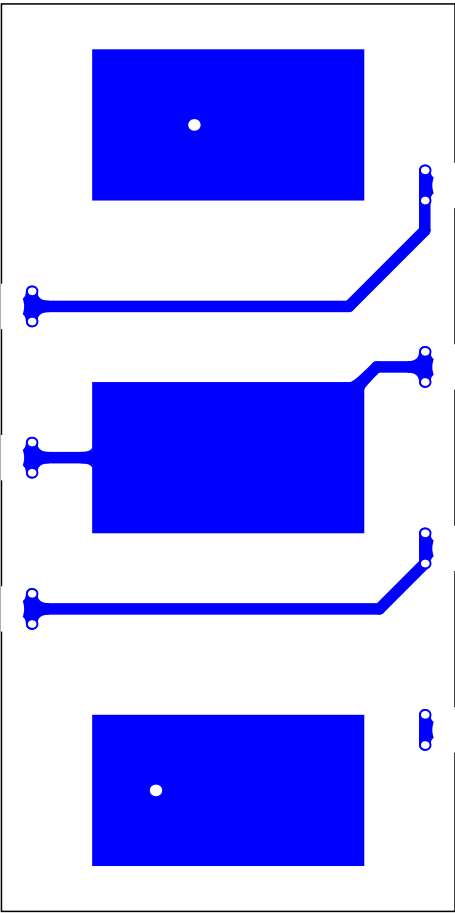


# SEMG Sensor

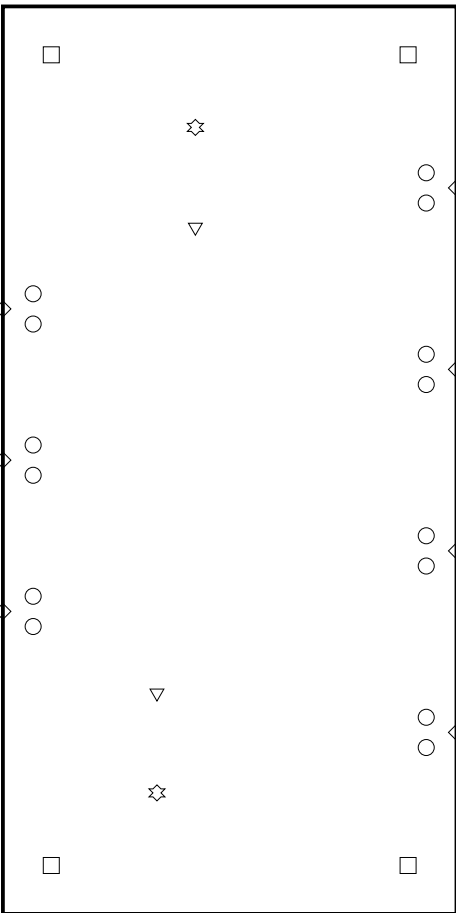
Top Layer (Scale 4:1)



Bottom Layer (Scale 4:1)



Drill Drawing View (Scale 4:1)



Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
○	14	0.25mm	Plated	
☆	2	0.38mm	Plated	
▽	2	0.85mm	Non-Plated	
◇	7	1.50mm	Plated	
□	4	2.00mm	Non-Plated	
29 Total				

Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
	Surface Material	0.01mm	Solder Resist	Solder Mask	GTS
Copper	Top Layer	0.04mm		Signal	GTL
Core		1.50mm	Core-043	Dielectric	
Copper	Bottom Layer	0.04mm		Signal	GBL
Surface Material	Bottom Solder	0.01mm	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO

Total thickness: 1.59mm



## WF TECNOLOGIA

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Projeto **SEMG Sensor**

Elaboração **Marlio** Aprovação **Roger** Layout **Natan**

Código **=Codigo** Revisão **R01** Folha **1/1**

Data **5/7/2024** Horário **9:00 PM** Tamanho **A3**

Arquivo **E:\WF\_Tecnologia\Roger\_Lakoski\_Mestrado\RL\_Sensor\_Proteses\Sensor\_Proteses\_Fabrication.PCBDwf**

Revisão Data Responsável Histórico

R00 03/11/2022 Natan MF =HIST01

R01 05/04/2022 Natan MF =HIST02